

Top view of a semiconductor device 100. The device features a central core 11, a square frame 12, and a larger square frame 13a, 13b. The device has four sets of pins: 14 on the top, 15 on the bottom, 16 on the left, and 17 on the right. A dashed line X-Y represents a horizontal axis, and a dashed line 17c-17d represents a vertical axis. The device is labeled 100.

A cross-sectional view of a semiconductor device. A central cavity (12) is formed in a substrate (11). The cavity is filled with a material (13a, 13b). A layer (14) is deposited on the cavity walls. A layer (15) is deposited on top of the cavity. A layer (16) is deposited on top of the layer (15). A layer (17a) is deposited on top of the layer (16). A layer (17b) is deposited on top of the layer (17a). A layer (17c) is deposited on top of the layer (17b). A layer (17d) is deposited on top of the layer (17c). A layer (18) is deposited on top of the layer (17d). A layer (19) is deposited on top of the layer (18).